

production

Solder reduces gaps inside insulation and increases effort

## DOCUMENT CHANGE REQUEST

1368 DCR number Changes required for: General Originator: LEROY Organisation: HYPERTAC Date: 2020/10/20 Date sent: 2020/07/28 Status: IMPLEMENTED Title: Connectors Electrical for Printed Circuit Boards Removable Contacts Crimp Wire-Wrap Solder and Number: 3401/016 Issue: 5 Other documents affected: Page: 69 Paragraph: 4.3.5 Original wording: (mating / unmating forces) indicate 0.7 N per contact max Proposed wording: For cases where contacts are soldered on PCB, efforts shall not be more than 1.0 N per contact For cases where contacts aren't soldered on PCB, efforts shall not be more than 0.7 N per contact Justification: This test is call during Endurance tests and we realize the test before and after cycles, parts fixed on PCB (ESCC3401 for qualification or for LAT) In production we have no possibility to reduce our criteria (0.7 N per contact) and it's not possible to solder the contact in

Attachments:
N/A
Modifications:
N/A
Approval signature:
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Date signed:
2020-10-20